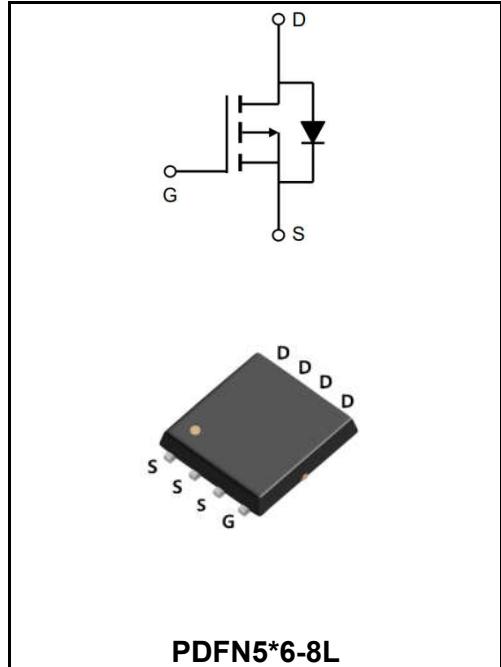


-60V P-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	-80A
V_{DSS}	-60V
$R_{DS(on)-typ}(@V_{GS}=-10V)$	< 11mΩ (Type: 9 mΩ)


Application

- ◆ Lithium battery protection
- ◆ Wireless impact
- ◆ Mobile phone fast charging

Product Specification Classification

Part Number	Package	Marking	Pack
YFW80P06NF	PDFN5*6-8L	YFW 80P06NF XXXXX	5000PCS/Tape

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	-60	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, $V_{GS} @ -10V^1$ @ $T_c=25^\circ\text{C}$	I_D	-80	A
Continuous Drain Current, $V_{GS} @ -10V^1$ @ $T_c=100^\circ\text{C}$	I_D	-38	A
Pulsed Drain Current ²	I_{DM}	-240	A
Single Pulse Avalanche Energy ³	E_{AS}	400	mJ
Avalanche Current	I_{AS}	41	A
Total Power Dissipation ⁴ @ $T_c=25^\circ\text{C}$	P_D	104	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	1.2	°C/W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	70	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	BV _{DSS}	-60	-68	-	V
BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA	ΔBV _{DSS/ΔTJ}	-	-0.035	-	V/°C
Static Drain-Source On-Resistance ²	V _{GS} =-10V, I _D =-20A	R _{DS(ON)}	-	9.0	11	mΩ
	V _{GS} =-4.5V, I _D =-15A		-	12	16	
Gate -Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	V _{GS(th)}	-1.2	-1.8	-2.5	V
V _{GS(th)} Temperature Coefficient		ΔV _{GS(th)}	-	4.28	-	mV/°C
Drain-Source Leakage Current	V _{DS} =-60V , V _{GS} =0V , T _J =25°C	I _{DSS}	-	-	1	μA
	V _{DS} =-60V , V _{GS} =0V , T _J =55°C		-	-	5	
Gate -Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Forward Transconductance	V _{DS} =-5V , I _D =-20A	g _{fs}	-	50	-	S
Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	R _g	-	2.0	-	Ω
Total Gate Charge(-4.5V)	V _{DS} =-30V V _{GS} =-10V I _D =-20A	Q _g	-	56	-	nC
Gate-Source Charge		Q _{gs}	-	11	-	
Gate-Drain Charge		Q _{gd}	-	9	-	
Turn-on delay time	V _{DD} =-30V V _{GS} =-10V I _D = -20A R _G =3Ω	t _{d(on)}	-	4.5	-	ns
Rise Time		T _r	-	2.5	-	
Turn-Off Delay Time		t _{d(OFF)}	-	14.5	-	
Fall Time		t _f	-	3.8	-	
Input Capacitance	V _{DS} =-15V V _{GS} =0V f=1MHz	C _{iss}	-	3500	-	pF
Output Capacitance		C _{oss}	-	600	-	
Reverse Transfer Capacitance		C _{rss}	-	25	-	
Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	I _s	-	-	-80	A
Pulsed Source Current ^{2,5}		I _{SM}	-	-	-240	A
Diode Forward Voltage ²	V _{GS} =0V , I _s =-1A , T _J =25°C	V _{SD}	-	-	-1.2	V

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、The EAS data shows Max. rating . The test condition is VDD =-48V,VGS =-10V,L=0.1mH,IAS =-41A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

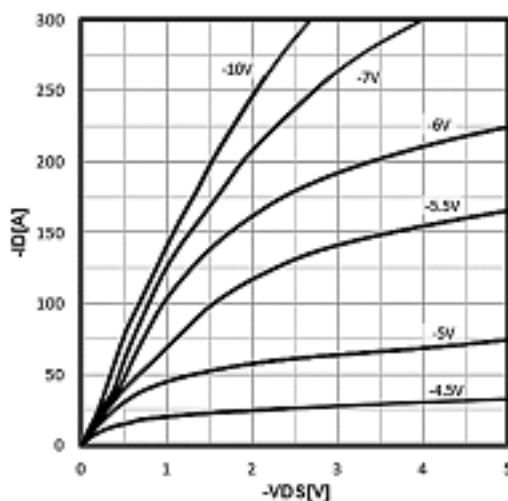


Figure 1. Type. Output Characteristics ($T_j=25\text{ }^{\circ}\text{C}$)

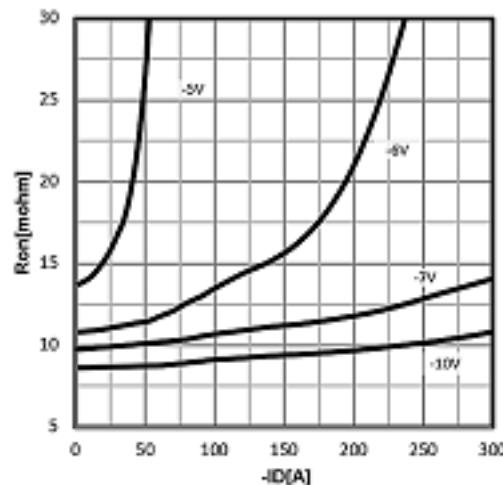


Figure 2. Type. drain-source on resistance

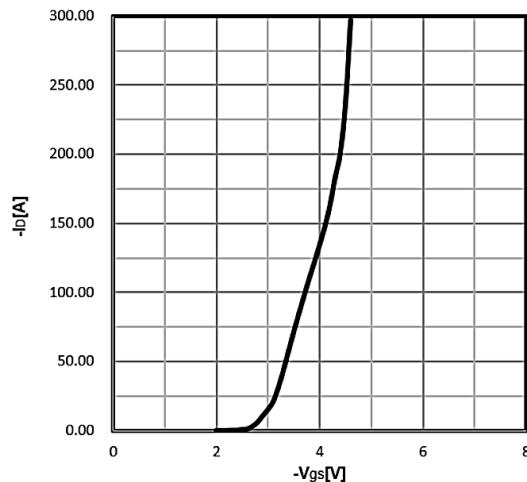


Figure 3. Type. transfer characteristics

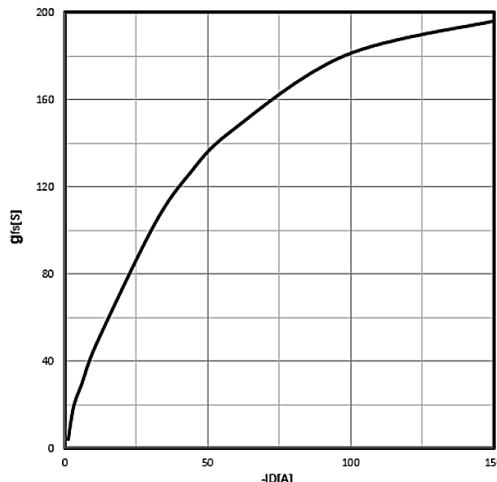


Figure 4. Type. forward transconductance

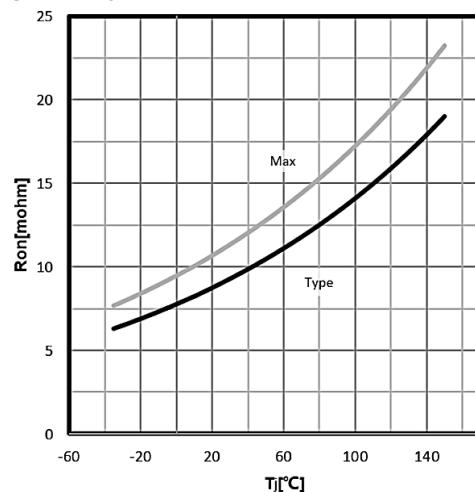


Figure 5. Drain-source on-state resistance
 $R_{DS(\text{on})} = f(T_j)$; $ID = 80\text{A}$; $VGS = 10\text{V}$

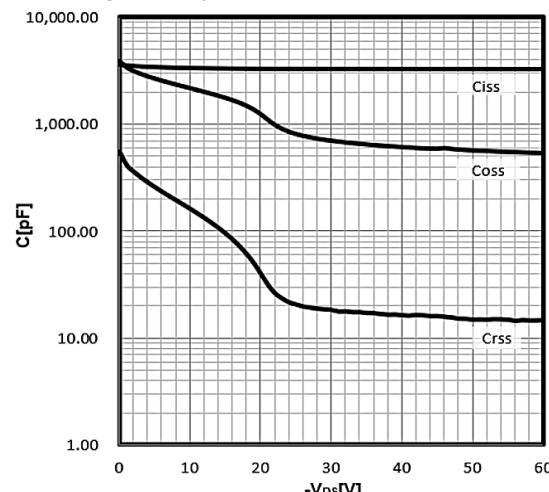
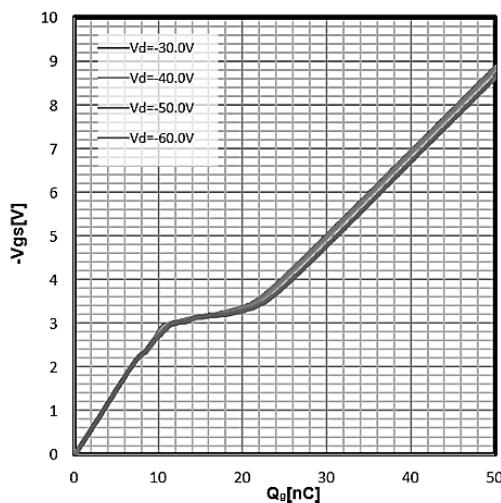
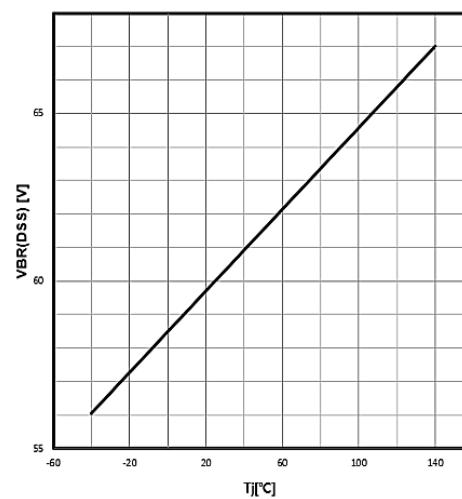


Figure 6 . Body-Diode Characteristics
 $C = f(VDS)$; $VGS = 0\text{V}$; $f = 1\text{MHz}$

Ratings and Characteristic Curves



**Figure 7. Typ. gate charge
 $V_{GS} = f(Q_{gate})$; $I_D = 20A$**



**Figure 8. Drain Current Derating
 $V_{BR(DSS)} = f(T_j)$; $I_D = 250\mu A$**

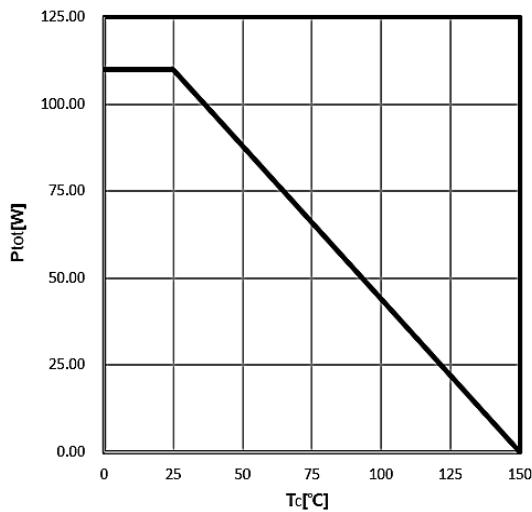


Figure 7. Power Dissipation

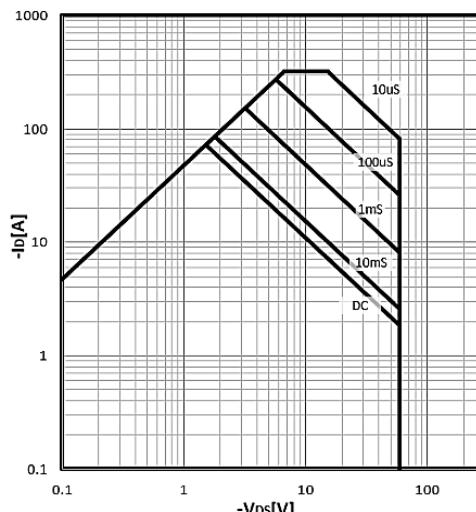


Figure 8. Safe operating area

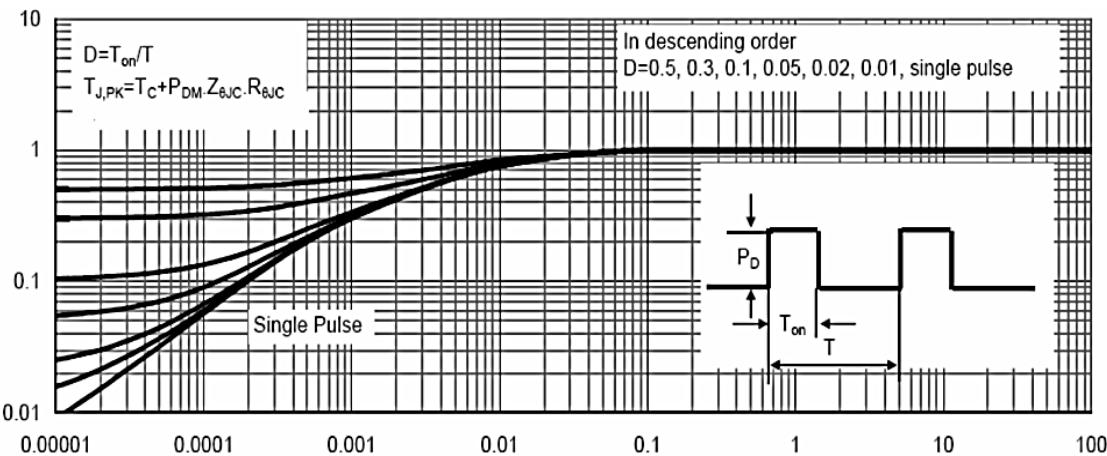
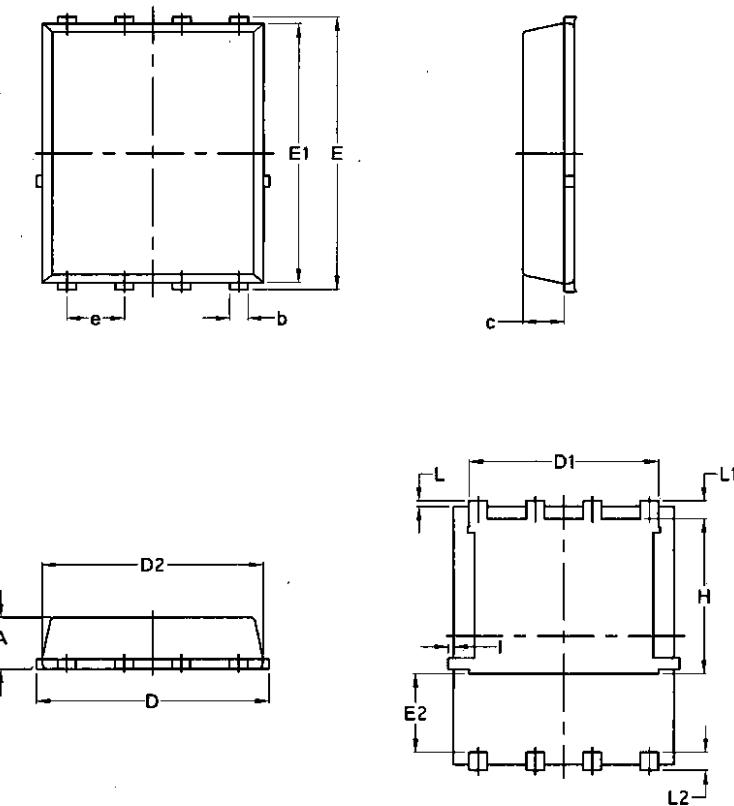


Figure 10. Max. transient thermal impedance

$$Z_{thJC} = f(t_p)$$

Package Outline Dimensions Millimeters
PDFN5*6-8L


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070